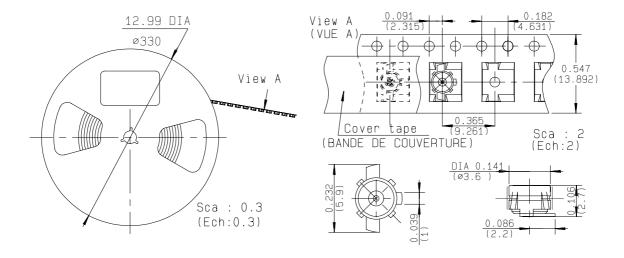
SMT TYPE - GOLD 0.2 - REEL OF 100

R210.408.012

Series: MMT



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	PHOSPHOR BRONZE BRASS PHOSPHOR BRONZE PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.2 OVER NICKEL 2 GOLD 0.2 OVER NICKEL 2

Issue: 0325 A

In the effort to improve our products, we reserve the right to make changes judged to be



SMT TYPE - GOLD 0.2 - REEL OF 100

R210.408.012

Series: MMT

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-8} \;\; \text{GHz} \end{array}$

VSWR 1.10 + 0.050 x F(GHz) Maxi

Insertion loss

O.20 $\sqrt{F(GHz)}$ dB Maxi

RF leakage

- (NA - F(GHz)) dB Maxi

RF leakage - (NA - F(GHz)) d Voltage rating 170 Veff Maxi Dielectric withstanding voltage 500 Veff mini

Insulation resistance $5000 \text{ M}\Omega \text{ mini}$

ENVIRONMENTAL

Operating temperature -55/+100 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

accouplt: 18Nmax / desacc.: 7Nmin

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

NA N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0.100** g

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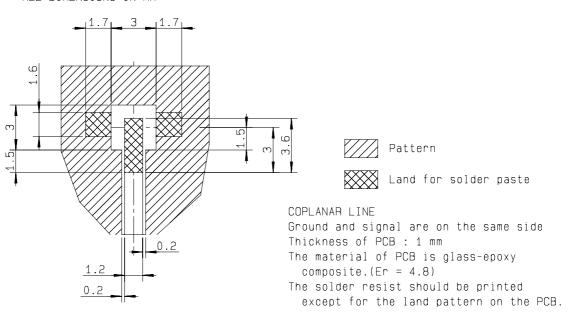
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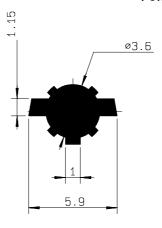
MMT SERIES - INFORMATION

ALL DIMENSIONS IN MM



ALL DIMENSIONS IN MM

SHADOW OF MMT RECEPTACLE FOR VIDEO CAMERA



Issue: 0325 A

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SMT TYPE - GOLD 0.2 - REEL OF 100

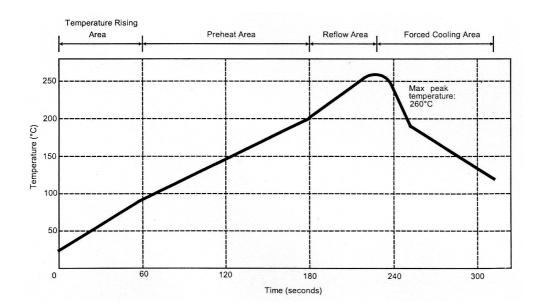
R210.408.012

Series: MMT

SOLDER PROCEDURE OF MMT RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- 1 Deposition of solder paste Sn Ag4 Cu0.5 on mounting zone by screen printing application. We recommend a Low Residue Solid Flux.
 - We advise a thickness of 200 microns (7.800 microinches). Verify that the edges of the prined zone are clean.
- 2 Placement of the receptacle on the mounting zone with an automatic machine of « pick and place » type. A video camera is recommanded for positioning of the component. (see page 3) Adhesive agents must not be used on the receptacle.
- 3 Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4 Cleaning of printed circuit boards
- 5 Verification of solder joints and position of the component by visual inspection

Note: The MMT receptacle and the MMT plug must not be mated before completion of this procedure.



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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necessary.

